

<b>PATENT ASSIGNMENT COVER SHEET</b>
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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
YA-CHIN CHIU	09/10/2020
MING-HSIEN LIN	09/10/2020
CHIA-TUNG HSU	09/10/2020
LUN-CHIEH CHIU	09/21/2020
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.
<b>Street Address:</b>	8, LI-HSIN RD. 6
<b>Internal Address:</b>	HSINCHU SCIENCE PARK
<b>City:</b>	HSINCHU
<b>State/Country:</b>	TAIWAN
<b>Postal Code:</b>	300-78
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	17989528
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.</i>	
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<b>Correspondent Name:</b>	R. BURNS ISRAELSEN
<b>Address Line 1:</b>	MASCHOFF BRENNAN
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<b>ATTORNEY DOCKET NUMBER:</b>	T1516.10769US03
<b>NAME OF SUBMITTER:</b>	R. BURNS ISRAELSEN
<b>SIGNATURE:</b>	/R. Burns Israelsen, Reg. No. 42685/
<b>DATE SIGNED:</b>	11/21/2022
<b>Total Attachments: 2</b>	

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**ASSIGNMENT**

This assignment agreement is applicable to an invention entitled (Invention Title) \_\_\_\_\_  
SEMICONDUCTOR STRUCTURE AND MANUFACTURING METHOD THEREOF

The PATENT RIGHTS referred to in this agreement are:

(check one)  a patent application for this invention, executed by the ASSIGNOR(S)  
 concurrently with this assignment.

U.S. patent application Serial No. 17/160,251, filed January 27, 2021

a U.S. patent application based on PCT International Application

No. \_\_\_\_\_ filed on (date) \_\_\_\_\_ (U.S. patent application  
 Serial No. \_\_\_\_\_, if known).

U.S. patent No. \_\_\_\_\_, issued \_\_\_\_\_.

The PATENT RIGHTS also include all divisions, reissues, continuations and extensions of  
 the patents and patent applications identified above.

The PATENT RIGHTS assigned under this agreement are:

U.S. patent rights only.

The ASSIGNOR(S) referred to in this agreement is (or are) the inventor(s) whose signatures  
 appear on page 2 of this Assignment and any Supplemental Sheet(s).

The ASSIGNEE referred to in this agreement is:

(Name of Assignee) TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY,  
LTD.

(Address) 8, Li-Hsin Rd. 6, Hsinchu Science Park, Hsinchu 300-78, Taiwan, R.O.C.

The ASSIGNEE is:

(check one)  An individual.

A Partnership.

A Corporation of TAIWAN, R.O.C. (specify state or country)

(other) \_\_\_\_\_

The ASSIGNOR(S), in consideration of \$10.00 paid by the ASSIGNEE, and other good and  
 valuable consideration, receipt of which is acknowledged, hereby assign(s) the following  
 rights to the ASSIGNEE, its successors and assigns:

the full and exclusive right to the invention;

the entire right, title and interest in and to the PATENT RIGHTS;

the right to sue and recover for any past infringement; and

the right to claim priority under 35 USC 119, 35 USC 120, or any other applicable  
 provisions, based on any earlier patent applications for this invention.

THIS IS PAGE 2 OF AN ASSIGNMENT FROM THE INVENTOR(S) TO  
ASSIGNEE: TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.

INVENTION TITLE: SEMICONDUCTOR STRUCTURE AND MANUFACTURING  
METHOD THEREOF

As to all U.S. patent applications assigned under this agreement, the ASSIGNOR(S) hereby authorize(s) and request(s) the Commissioner of Patents and Trademark to issue all Letters Patent to the ASSIGNEE as the assignee of the entire right, title and interest, for the sole use and enjoyment of said ASSIGNEE, its successors and assigns.

Further, the ASSIGNOR(S) agree(s) to communicate to said ASSIGNEE, or its representatives, any fact known to the ASSIGNOR(S) with respect to said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuation, substitute, renewal, reexamination and reissue applications, execute all necessary assignment papers to cause and all Letter Patent to be issued to said ASSIGNEE, make all rightful oaths and generally do everything necessary or desirable to aid said ASSIGNEE, its successors and assigns, to obtain and enforce proper protection for said invention.

The ASSIGNOR(S) authorize(s) the attorneys and agents who have the power of attorney in this application to check any appropriate boxes and to insert the Serial Number and filing date in this document after it has been executed.

<u>Ya-Chin CHIU</u>	<u>Ya-Chin Chiu</u>	<u>2020.9.10</u>
Name of sole or first inventor	Signature	Date

<u>Ming-Hsien LIN</u>	<u>Ming-Hsien LIN</u>	<u>2020.9.10</u>
Name of second inventor, if any	Signature	Date

<u>Chia-Tung HSU</u>	<u>Chia-Tung Hsu</u>	<u>2020.9.10</u>
Name of third inventor, if any	Signature	Date

<u>Lun-Chieh CHIU</u>	<u>Lun-Chieh Chiu</u>	<u>2020.9.21</u>
Name of fourth inventor, if any	Signature	Date